

BASIC BLADE & BEAM HEADER & SOCKET

(0.80 mm) .0315" PITCH • BTE/BSE SERIES



BTE
Mates:
BSE

BSE
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BTE

SPECIFICATIONS

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating:
2 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
225 VAC with 5 mm Stack Height
Max Cycles:
100

PROCESSING

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (020-080)
(0.15 mm) .006" max (100-120)*
*(.004" stencil solution may be available; contact ipg@samtec.com)
Board Stacking:
For applications requiring more than two connectors per board or 80 positions or higher, contact ipg@samtec.com

ALSO AVAILABLE

MOQ Required

30 μ" (0.76 μm) Gold
Edge Mount Capability
Friction Lock option
11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)



Note:
Some lengths, styles and options are non-standard, non-returnable.

BTE	NO. OF POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	A	OTHER OPTION
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-020, -040, -060,
-080, -100, -120

Specify
LEAD
STYLE
from
chart

-F
= Gold Flash on contact,
Matte Tin on tail

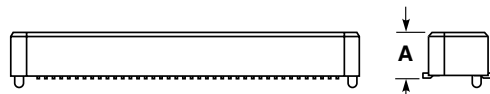
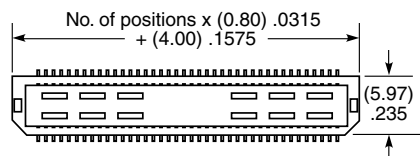
-L
= 10 μ" (0.25 μm)
Gold on contact,
Matte Tin on tail

-C*
= Electro-Polished Selective
50 μ" (1.27 μm) min
Au over 150 μ" (3.81 μm)
Ni on Signal Pins in contact
area, Matte Tin over
50 μ" (1.27 μm) min
Ni on all solder tails
(*-C Plating passes
10 year MFG testing)

-K
= (7.00 mm)
.275" DIA
Polyimide Film
Pick & Place Pad

-TR
= Tape & Reel
(80 positions
maximum)

-FR
= Full Reel
Tape & Reel
(must order
maximum
quantity per
reel; contact
Samtec for
quantity breaks)
(80 positions
maximum)



LEAD STYLE	A
-01	(4.27) .168
-02	(7.21) .284

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"
-02	(8.00 mm) .315"

*Processing conditions will affect mated height.

BSE	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
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-020, -040, -060,
-080, -100, -120

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Matte Tin on tail

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Gold on contact,
Matte Tin on tail

-C*
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50 μ" (1.27 μm) min
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(80 positions
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Tape & Reel
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